

REMARKS

Applicants respectfully request reconsideration in view of the reasons that follow.

New claims 20-25 have been added.

Claims 1-25 are pending in this application. Claims 7-19 have been withdrawn from consideration.

Priority

Applicants note that the Office has not acknowledged Applicants' claim for foreign priority and receipt of a copy of the certified copy. Applicants respectfully request that the Office acknowledge Applicants' claim for foreign priority and receipt of a copy of the certified copy with the next Office correspondence.

Information Disclosure Statement

Applicants wishes to thank the Office for providing a signed copy of the Information Disclosure Statement filed on September 12, 2003. However, the Office did not initial the reference, JP 2002-129803, listed in the Information Disclosure Statement. The Office Action did not state why this reference was not initialed. Applicants respectfully request that the Office initial this reference and attach a copy of the initialed SB/08 form to the next Office correspondence. For convenience, a copy of JP 2002-129803 is attached to this response.

Claim 16

Applicant submits that claim 16, which is currently withdrawn from consideration but originally depends upon claim 1, should be considered along with claims 1-6 and 20-25. Consideration of claim 16 is respectfully requested.

Rejection under 35 U.S.C. § 102

Claims 1-6 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 6,068,523 (hereafter "Takahashi"). This rejection is respectfully traversed.

Claim 1 recites a bonding structure of plastic parts that includes a first plastic part comprising an insert-molded wiring board at least partially surrounded by plastic and at least

one wiring board holding hole extending through the plastic that at least partially surrounds the wiring board, wherein the wiring board is connected to a connection terminal, a second plastic part comprising a bonding face, wherein excess plastic material selectively located in an area surrounding said at least one holding hole is bonded to the bonding face of the second plastic part.

Claim 2 recites a bonding structure of plastic parts that includes a first plastic part comprising an insert-molded wiring board at least partially surrounded by plastic wherein the wiring board is connected to a connection terminal, and a second plastic part comprising a terminal introducing hole in which said connection terminal is introduced, wherein excess plastic material selectively located in an area surrounding said connection terminal and said terminal introducing hole are bonded to each other.

Claim 3 recites a bonding structure of plastic parts that includes a first plastic part comprising an insert-molded wiring board at least partially surrounded by plastic and at least one wiring board holding hole extending through the plastic that at least partially surrounds the wiring board, wherein the wiring board is connected to a connection terminal, and a second plastic part comprising a bonding face and a terminal introducing hole in which said connection terminal is introduced, wherein excess plastic material selectively located in an area surrounding said at least one holding hole is bonded to the bonding face of the second plastic part, wherein excess plastic material selectively located in an area surrounding said connection terminal and said terminal introducing hole are bonded to each other.

Takahashi discloses a connector-incorporated case 20 that is made by insert-molding bus bars 42 to form a primary molded member 40, providing a resin spacer 47 on exposed areas 45 of the bus bars 42, and then integrally molding a secondary molded member 30 on the primary molded member 40 and resin spacer 47. See Takahashi at col. 4, lines 37-43 and col. 5, lines 3-16.

However, Takahashi does not disclose a surrounding of a holding hole for holding an insert-molded wiring board “wherein excess plastic material selectively located in an area surrounding said at least one holding hole is bonded to the bonding face of the second plastic part,” as recited in claims 1 and 3. Takahashi is silent in regard to this claimed structure. Furthermore, Takahashi does not disclose a surrounding of a connection terminal “wherein

excess plastic material selectively located in an area surrounding said connection terminal and said terminal introducing hole are bonded to each other," as recited in claims 2 and 3.

Takahashi is silent in regard to this structure as well. Therefore, Takahashi does not disclose all of the subject matter recited in claims 1-3. Claims 4-6 and 20-23 depend upon claims 1-3 and are allowable over Takahashi for at least the same reasons. Withdrawal of this rejection is respectfully requested.

Applicants believe that the present application is now in condition for allowance. Favorable reconsideration of the application as amended is respectfully requested.

The Examiner is invited to contact the undersigned by telephone if it is felt that a telephone interview would advance the prosecution of the present application.

The Commissioner is hereby authorized to charge any additional fees which may be required regarding this application under 37 C.F.R. §§ 1.16-1.17, or credit any overpayment, to Deposit Account No. 19-0741. Should no proper payment be enclosed herewith, as by a check or credit card payment form being in the wrong amount, unsigned, post-dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 19-0741. If any extensions of time are needed for timely acceptance of papers submitted herewith, Applicant hereby petitions for such extension under 37 C.F.R. §1.136 and authorizes payment of any such extensions fees to Deposit Account No. 19-0741.

Respectfully submitted,

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Date _____

By 

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